

STPS30SM60S

Power Schottky rectifier

Features

- High current capability
- Avalanche rated
- Low forward voltage drop
- High frequency operation

Description

The STPS30SM60S is a single Schottky diode, suited for high frequency switch mode power supply.

Packaged in TO-220AB, I²PAK and D²PAK, this device is intended to be used in notebook, game station and desktop adapters, providing in these applications a good efficiency at both low and high load.

Table 1. Device summary

Symbol	Value
I _{F(AV)}	30 A
V _{RRM}	60 V
V _F (typ)	0.405 V
T _j (max)	150 °C

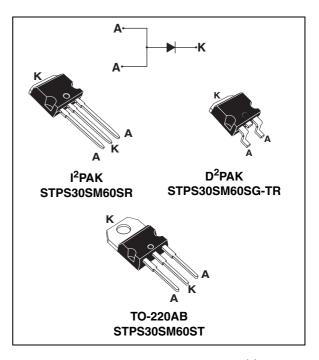
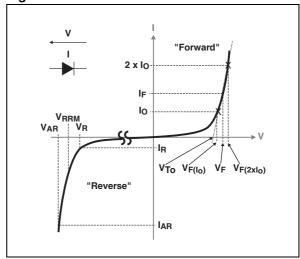


Figure 1. Electrical characteristics^(a)



V_{ARM} and I_{ARM} must respect the reverse safe operating area defined in *Figure 12*. V_{AR} and I_{AR} are pulse measurements (t_p < 1 μs). V_R, I_R, V_{RRM} and V_F, are static characteristics

Characteristics STPS30SM60S

Characteristics

Absolute ratings (limiting values with terminals 1 and 3 short circuited at Table 2. 25 °C, unless otherwise specified)

Symbol	Parameter			Value	Unit	
V_{RRM}	Repetitive peak reverse voltage			60	V	
I _{F(RMS)}	Forward rms current			90	Α	
I _{F(AV)}	Average forward current, a	ard current, $\delta = 0.5$ $T_c = 125 ^{\circ}\text{C}$ Per package			30	Α
I _{FSM}	Surge non repetitive forward current $t_p = 10 \text{ ms sine-wave}$			600	Α	
P _{ARM} ⁽¹⁾	Repetitive peak avalanche	nche power $T_j = 25 ^{\circ}\text{C}, t_p = 1 \mu\text{s}$		28000	W	
V _{ARM} ⁽²⁾	Maximum repetitive peak avalanche voltage	t _p < 1 μs, T _j < 150 °C, I _{AR} < 105 A		80	V	
V _{ASM} ⁽²⁾	Maximum single-pulse peak avalanche voltage	t _p < 1 μs, T _j < 150 °C, I _{AR} < 105 A		80	V	
T _{stg}	Storage temperature range			-65 to +175	°C	
Tj	Maximum operating junction temperature ⁽³⁾			150	°C	

For temperature or pulse time duration deratings, please refer to Figure 4 and 5. More details regarding the avalanche energy measurements and diode validation in the avalanche are provided in the application notes AN1768 and AN2025.

Table 3. Thermal resistance

Symbol	Parameter	Value	Unit
R _{th(j-c)}	Junction to case	1.0	°C/W

Table 4. Static electrical characteristics (terminals 1 and 3 short circuited)

Symbol	Parameter	Test conditions		Min.	Тур.	Max.	Unit
I _R ⁽¹⁾	Reverse leakage	T _j = 25 °C	V - V	-	30	135	μΑ
'R`´	R`´ current	T _j = 125 °C	$V_R = V_{RM}$	-	20	80	mA
	V _F ⁽²⁾ Forward voltage drop	T _j = 25 °C	I _F = 15 A	-	0.490	0.530	
V (2)		T _j = 125 °C		-	0.405	0.450	V
v F` ′		T _j = 25 °C	I _F = 30 A	-	0.560	0.615	V
		T _j = 125 °C		-	0.500	0.570	

^{1.} Pulse test: $t_p = 5$ ms, $\delta < 2\%$

To evaluate the conduction losses use the following equation: P = 0.440 x $I_{F(AV)}$ + 0.0043 x $I_{F}^2(RMS)$

$$P = 0.440 \times I_{F(AV)} + 0.0043 \times I_{F(RMS)}^2$$

^{2.} See Figure 12

 $[\]frac{\text{dPtot}}{\text{dTj}} < \frac{1}{\text{Rth(j-a)}} \text{ condition to avoid thermal runaway for a diode on its own heatsink}$

^{2.} Pulse test: t_p = 380 μ s, δ < 2%

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Figure 2. Average forward power dissipation Figure 3. Average forward current versus versus average forward current ambient temperature ($\delta = 0.5$)

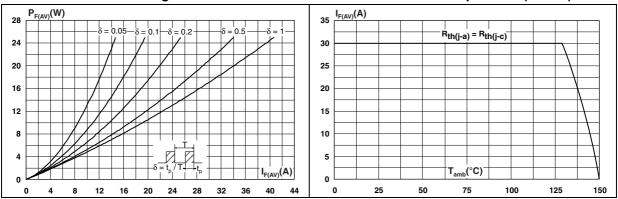


Figure 4. Normalized avalanche power derating versus pulse duration

Figure 5. Normalized avalanche power derating versus junction temperature

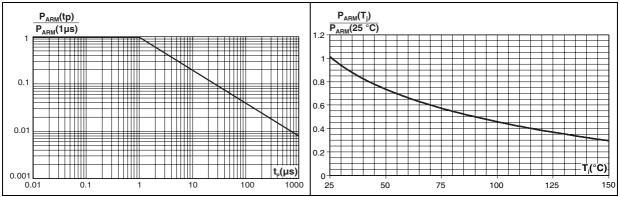
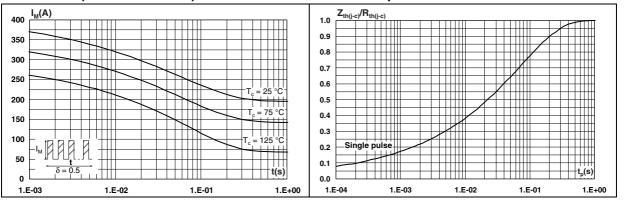


Figure 6. Non repetitive surge peak forward current versus overload duration (maximum values)

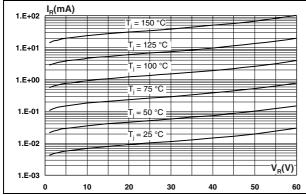
Figure 7. Relative variation of thermal impedance junction to case versus pulse duration



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Figure 8. Reverse leakage current versus reverse voltage applied (typical values)

Figure 9. Junction capacitance versus reverse voltage applied (typical values)



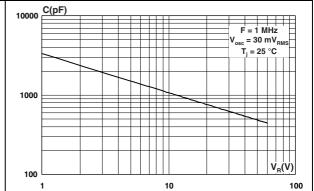
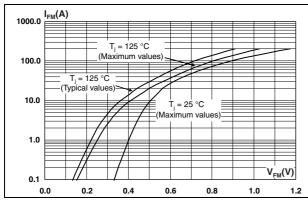


Figure 10. Forward voltage drop versus forward current

Figure 11. Thermal resistance junction to ambient versus copper surface under tab



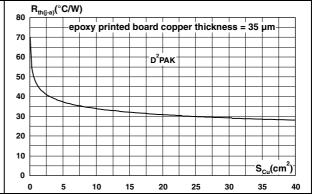
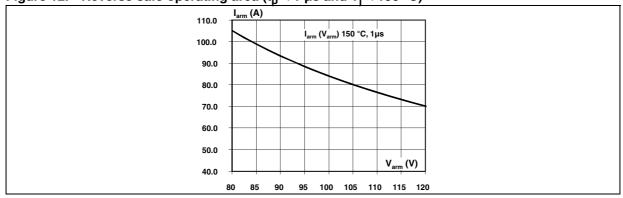


Figure 12. Reverse safe operating area ($t_p < 1 \mu s$ and $T_i < 150 \,^{\circ}C$)



2 Package information

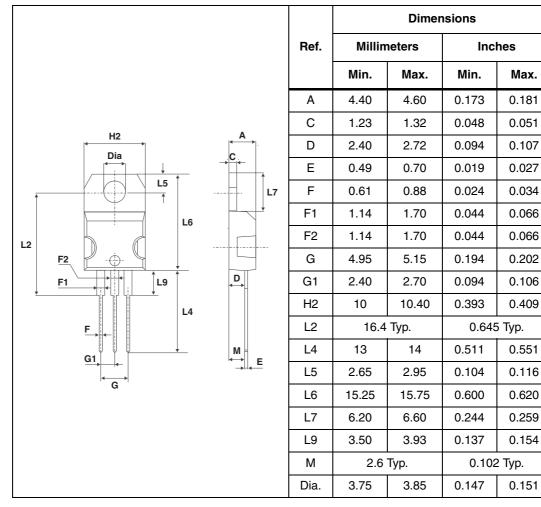
Epoxy meets UL94, V0

Cooling method: by conduction (C)

Recommended torque value: 0.4 to 0.6 N⋅m

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK[®] is an ST trademark.

Table 5. TO-220AB dimensions



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Table 6. D²PAK dimensions

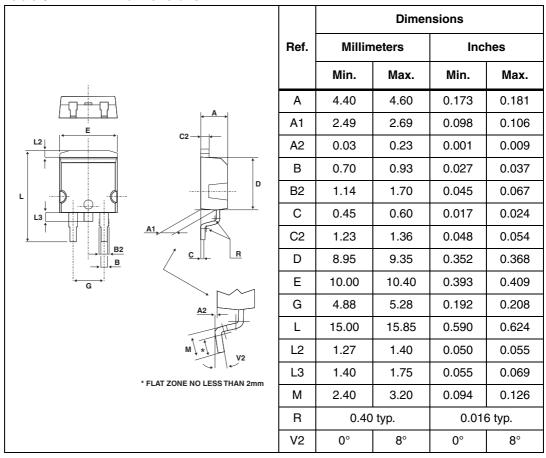


Figure 13. D²PAK footprint (dimensions in mm)

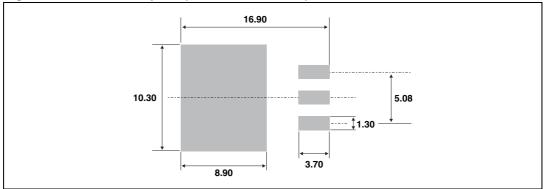
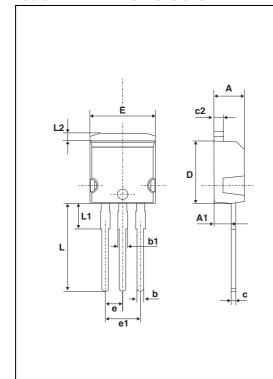


Table 7. I²PAK dimensions



	Dimensions				
Ref.	Millimeters		Inches		
	Min.	Max.	Min.	Max.	
Α	4.40	4.60	0.173	0.181	
A1	2.40	2.72	0.094	0.107	
b	0.61	0.88	0.024	0.035	
b1	1.14	1.70	0.044	0.067	
С	0.49	0.70	0.019	0.028	
c2	1.23	1.32	0.048	0.052	
D	8.95	9.35	0.352	0.368	
е	2.40	2.70	0.094	0.106	
e1	4.95	5.15	0.195	0.203	
Е	10	10.40	0.394	0.409	
L	13	14	0.512	0.551	
L1	3.50	3.93	0.138	0.155	
L2	1.27	1.40	0.050	0.055	

Ordering information STPS30SM60S

3 Ordering information

Table 8. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
STPS30SM60ST	STPS30SM60ST	TO-220AB	2.2 g	50	Tube
STPS30SM60SR	STPS30SM60SR	I ² PAK	1.49 g	50	Tube
STPS30SM60SG-TR	STPS30SM60SG	D ² PAK	1.48 g	1000	Tape and reel

4 Revision history

Table 9. Revision history

Date	Revision	Changes
24-Oct-2011	1	First issue.

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